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(12) United States Design Patent
Mori et al.

(10) **Patent No.: US D810,707 S**

(45) **Date of Patent: ** Feb. 20, 2018**

(54) **FLEXIBLE PRINTED WIRING BOARD WITH DEVICE**

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(**) Term: **15 Years**

(21) Appl. No.: **29/586,563**

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Related U.S. Application Data

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(30) **Foreign Application Priority Data**

May 28, 2014 (JP) 2014-011388
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(51) **LOC (11) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/182**

(58) **Field of Classification Search**
USPC D13/155, 182; 174/68.1, 68.2, 68.3, 250, 174/253, 254, 255, 256, 257, 258, 260
(Continued)

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(57) CLAIM

The ornamental design for a flexible printed wiring board with device, as shown and described.

DESCRIPTION

FIG. **1** is a front view of a flexible printed wiring board with device shown in a used condition mounted on a photovoltaic power device for a photovoltaic module or a light emitting diode device for a light emitting diode module shown in broken lines showing our new design;
FIG. **2** is a rear view thereof;
FIG. **3** is a top plan view thereof;
FIG. **4** is a bottom plan view thereof;
FIG. **5** is a right side view thereof;
FIG. **6** is a left side view thereof;
FIG. **7** is an enlarged top plan view of a portion taken along lines **7-7** of FIG. **3**;
FIG. **8** is an enlarged bottom plan view of a portion taken along lines **8-8** of FIG. **4**;
FIG. **9** is an enlarged front view of a portion taken along lines **9-9** of FIG. **1**;
FIG. **10** is an enlarged rear view of a portion taken along lines **10-10** of FIG. **2**;
FIG. **11** is a right side view of FIG. **7**; and,
FIG. **12** is an enlarged left side view of FIG. **6**.

The even dashed broken lines shown in the drawings represent portions of the flexible printed wiring board with device that form no part of the claimed design. The long

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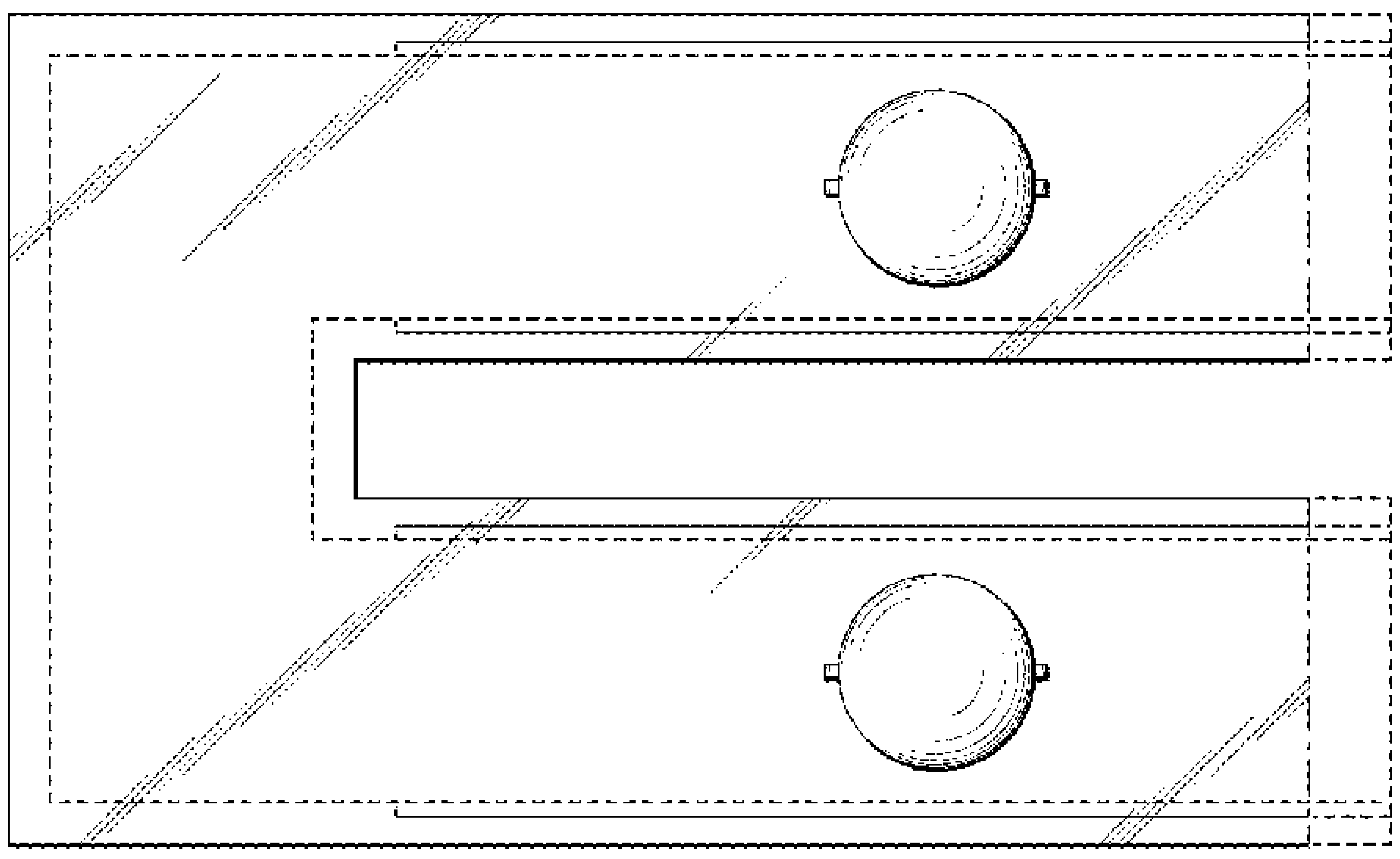

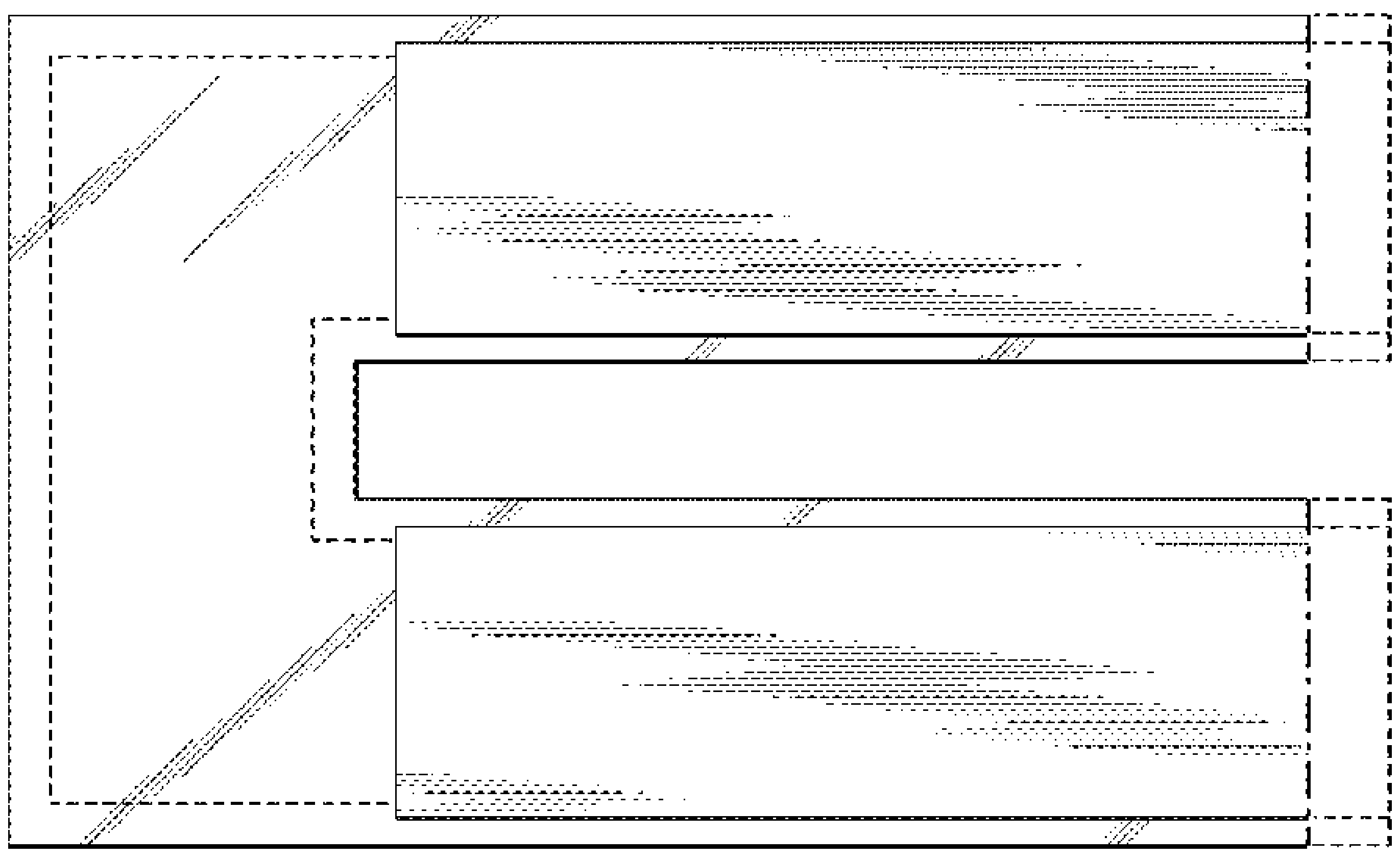

dashed and short dashed line indicates only a boundary line between the claimed and unclaimed areas of the design.

1 Claim, 4 Drawing Sheets

(58) **Field of Classification Search**

CPC H05K 3/36; H05K 3/361; H05K 3/363; H05K 3/365; H05K 3/40; H05K 3/4007; H05K 3/4015; H05K 3/0062; H05K 3/28; H05K 3/281; H05K 2201/0999; H05K 2201/09818; H05K 2201/04; H05K 2201/05; H05K 2201/051; H05K 2201/052; H05K 2201/053; H05K 2201/055; H05K 2201/056; H05K 2201/057; H05K 2201/058; H05K 2201/0715; H05K 1/0393; H05K 1/118; H05K 1/028; H05K 1/0281; H05K 1/0283

See application file for complete search history.

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FIG.1

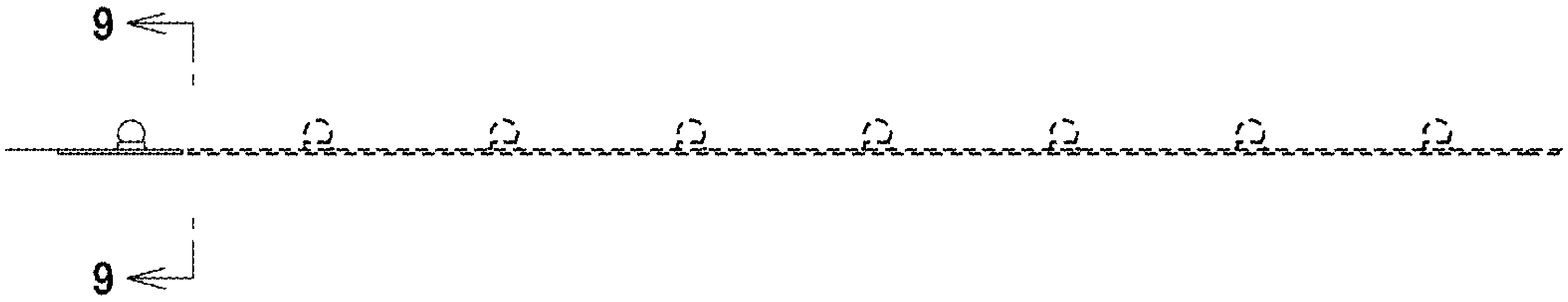

FIG.2

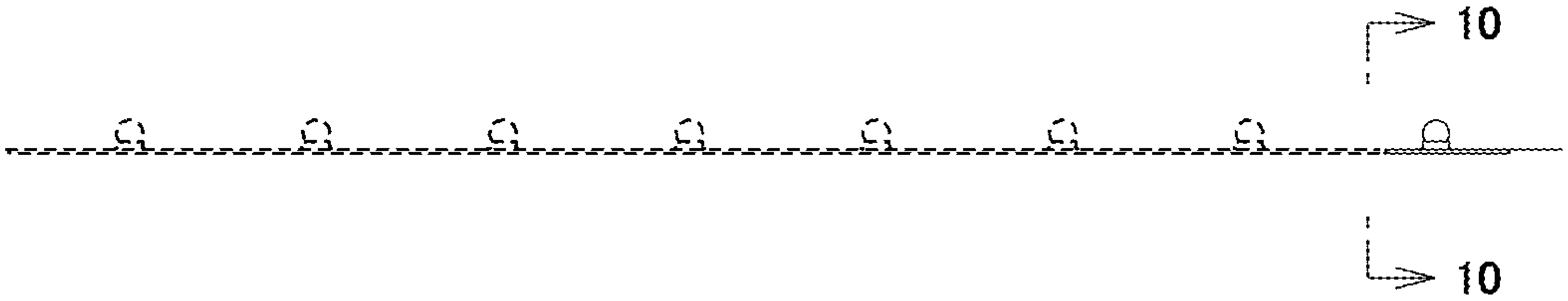

FIG.3

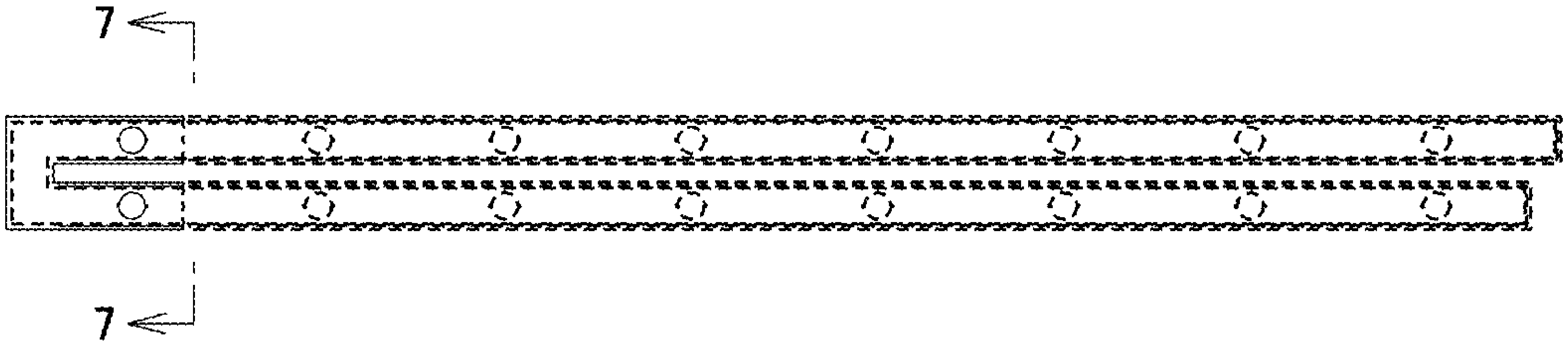

FIG.4

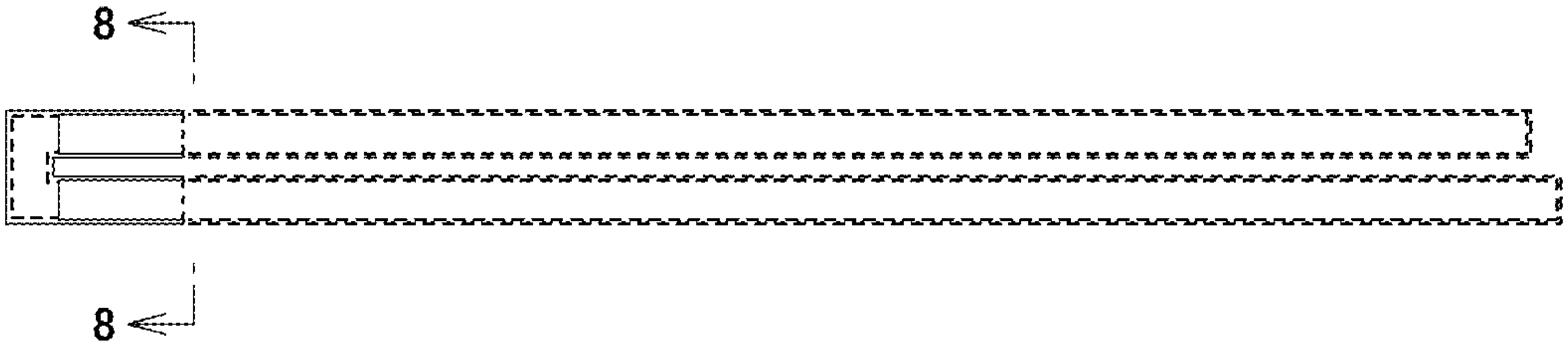

FIG.5

FIG.6

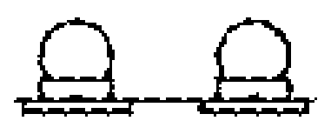

FIG.7

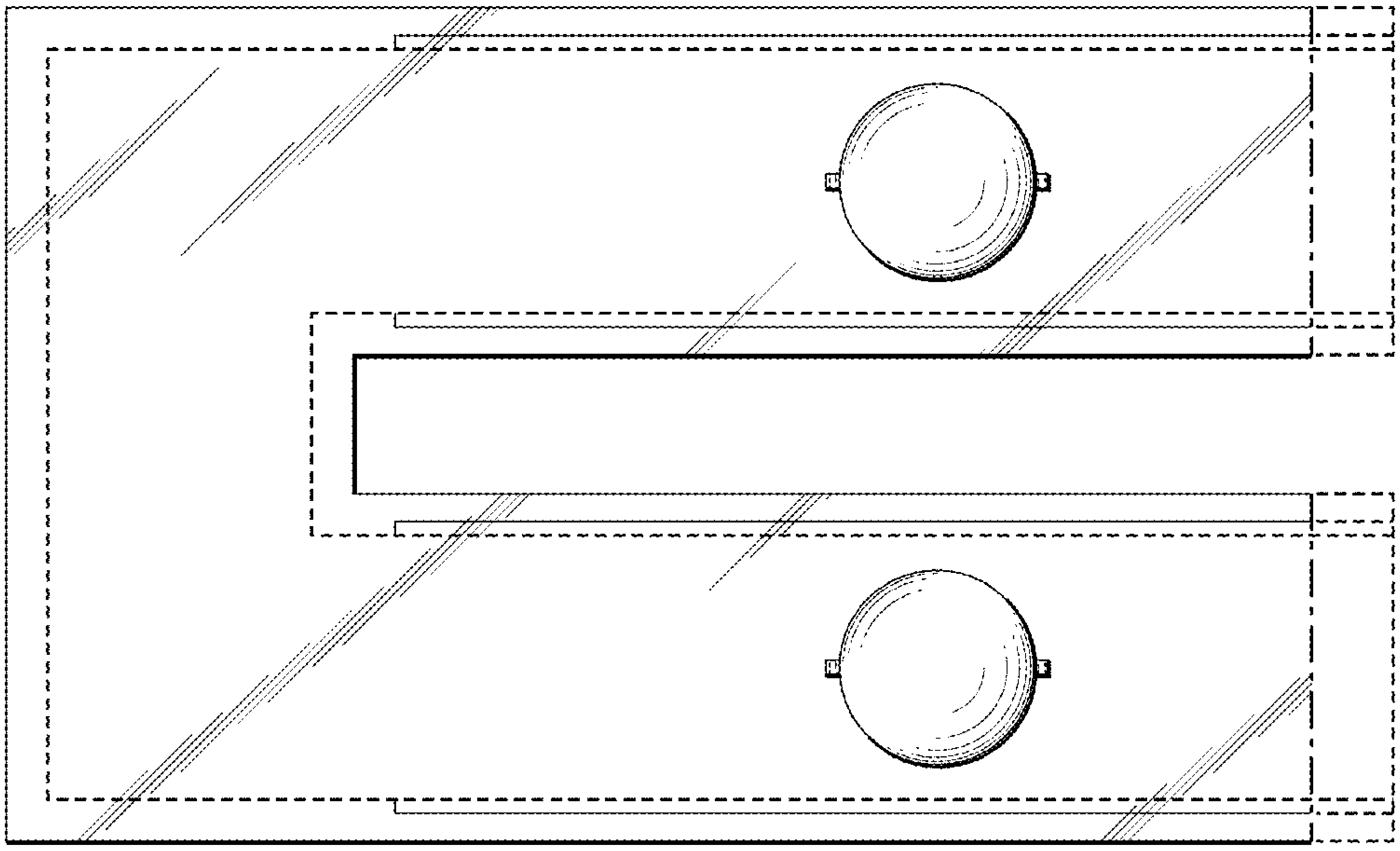

FIG.8

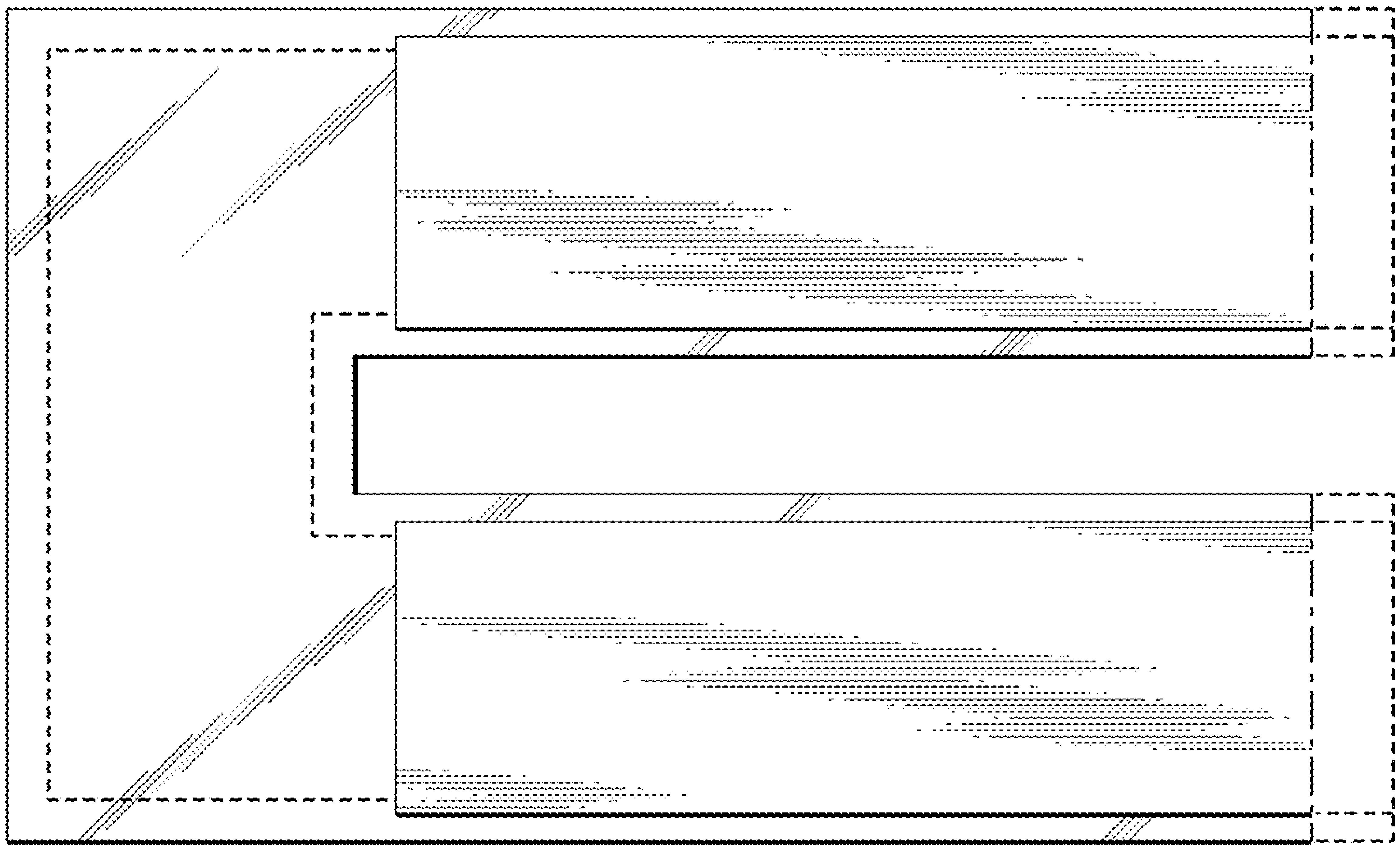

FIG.9

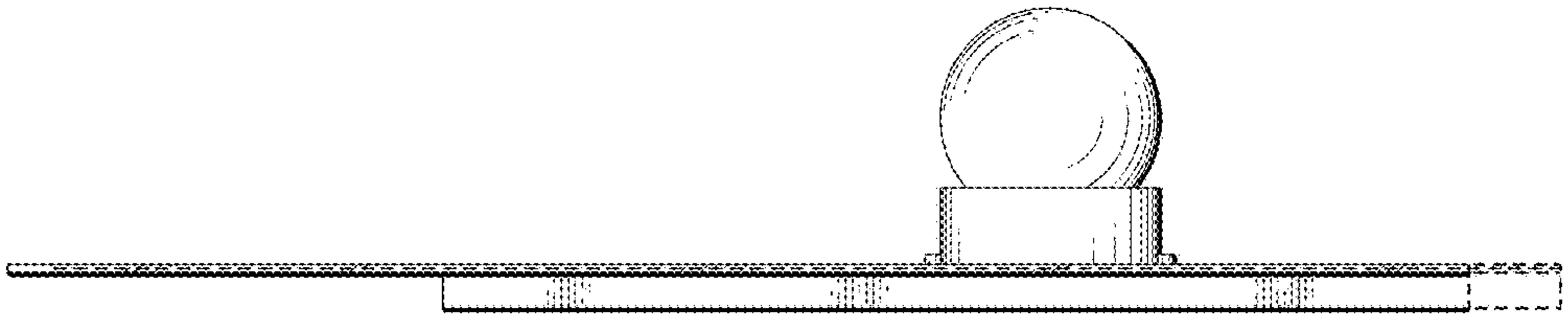

FIG.10

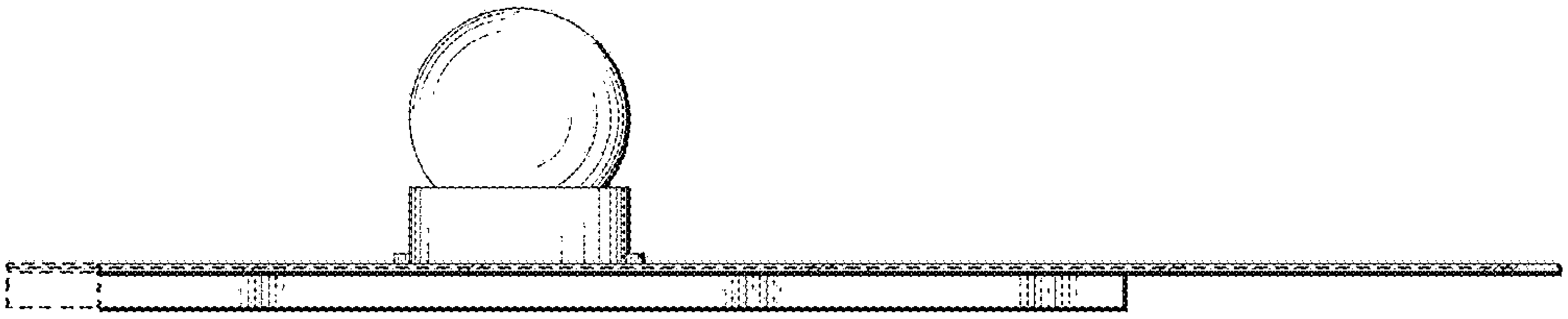

FIG.11

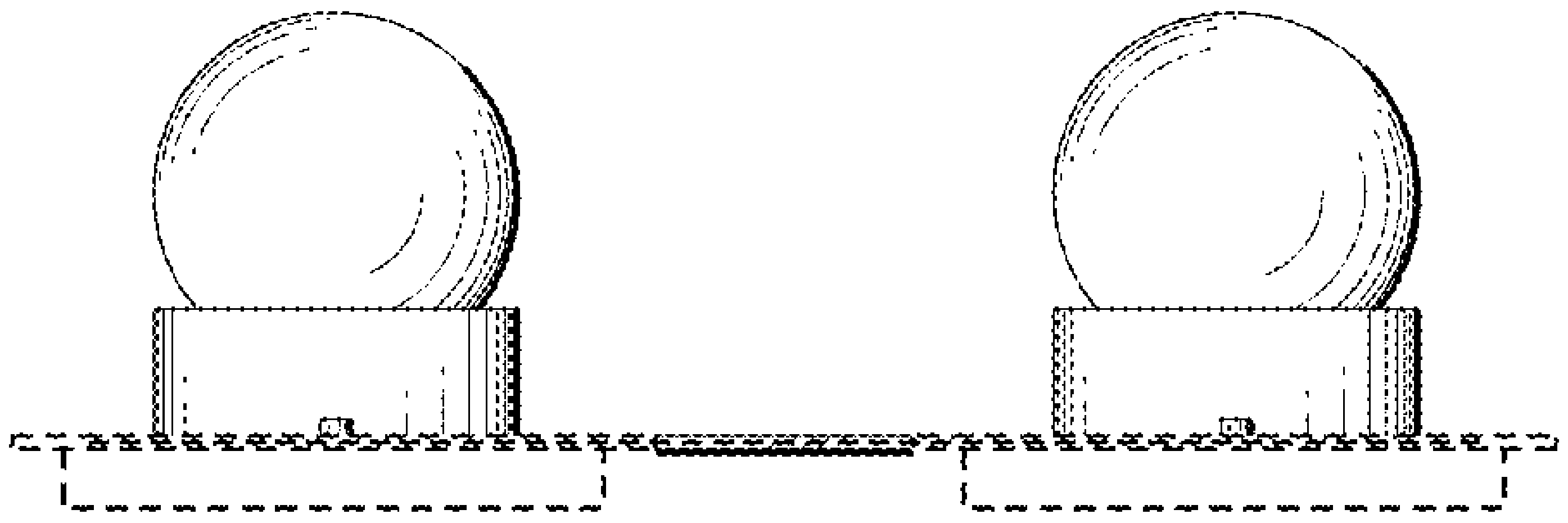

FIG.12